Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
		magnet$7 adj align$5	USPAT; EPO; JPO; DERWENT	OR	OFF	2002/02/05 08:56
		((438/15,110,113,114.ccls. and test$3) and (dic$5 or cut$5)) and (magnet$7 adj align$5)	USPAT; EPO; JPO; DERWENT	OR	OFF	2002/02/05 08:33
L3	111	("5073840" "5817535" "5858815" "6426642" "6214716" "6188232" "6163956" "6150193" "6060891" "6004867".pn.) and test$5 and (cut$5 or dic$6 or seperat$5 or saw$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/29 08:25
L4	1	("20010052642").PN.	US-PGPUB	OR	OFF	2005/01/29 08:25
L5	17	(("5242855") or ("3918148") or ("6175084") or ("5134539") or ("6297553") or ("5143865") or ("6389689") or ("6479887") or ("6252298") or ("6268236") or ("20010052642") or ("6163956") or ("6153448") or ("6064217") or ("6344401") or ("4781969") or ("5137836")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/29 08:55
S1	11	(("5242855") or ("3918148") or ("6175084") or ("5134539") or ("6297553") or ("5143865") or ("6389689") or ("6479887") or ("6252298") or ("6268236") or ("20010052642")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/29 08:15
S2	18	438/455,456,457,458,459,460,461, 462,464.ccls. and test$6 and (dic$4) and magnetic$6 and @ad<"20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/08 09:53
S3	13	438/455,456,457,458,459,460,461, 462,464.ccls. and align$6 and test$6 and (dic$4) and magnetic$6 and @ad<"20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/08 10:00
S4	88	"438"/$.ccls. and align$6 and test$6 and (dic$4) and magnetic$6 and @ad<"20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/08 09:54
S10	28	438/15,113,110,107,108,114,123, 455,456,457,458,459,460,461,462, 464.ccls. and align$6 and test$6 and (dic$4) and magnetic$6 and @ad<"20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/08 10:01

S11	1	("6165885").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/10/08 11:34
S12	348	(438/15).CCLS.	USPAT; USOCR	OR	OFF	2004/04/08 08:51
S13	258	(438/113).CCLS.	USPAT; USOCR	OR	OFF	2002/07/03 08:58
S14	94	(438/110).CCLS.	USPAT; USOCR	OR	OFF	2002/07/03 08:58
S15	59	(438/114).CCLS.	USPAT; USOCR	OR	OFF	2002/07/03 08:58
S16	681	438/15,110,113,114.ccls.	USPAT	OR	OFF	2002/12/19 14:38
S17	401	438/15,110,113,114.ccls. and test$3	USPAT	OR	OFF	2001/08/07 15:09
S18	272	(438/15,110,113,114.ccls. and test$3) and (dice$4 or cut$5)	USPAT	OR	OFF	2001/08/07 15:10
S19	901	438/15,110,113,114.ccls.	USPAT; EPO; JPO; DERWENT	OR	OFF	2002/02/04 09:53
S20	460	438/15,110,113,114.ccls. and test$3	USPAT; EPO; JPO; DERWENT	OR	OFF	2002/02/04 09:54
S21	325	(438/15,110,113,114.ccls. and test$3) and (dic$5 or cut$5)	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/06 09:25
S22	5	((("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697")).PN.	USPAT; USOCR	OR	OFF	2004/04/08 10:12
S23	7	((("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697") or ("5858815") or ("5137836")).PN.	USPAT; USOCR	OR	OFF	2002/02/05 09:49
S24	326	(438/15,110,113,114.ccls. and test$3) and (dic$5 or cut$5)	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/07 12:10
S25	170	((438/15,110,113,114.ccls. and test$3) and (dic$5 or cut$5)) and (align$5)	USPAT; EPO; JPO; DERWENT	OR	OFF	2002/02/05 08:32
S29	248	(magnet$7 adj align$5) and semiconductor	USPAT; EPO; JPO; DERWENT	OR	OFF	2002/02/05 08:57
S32	613	(magnet$7 adj align$5) and ring	USPAT; EPO; JPO; DERWENT	OR	OFF	2002/02/05 08:50
S33	47	((magnet$7 adj align$5) and ring) and semiconductor	USPAT; EPO; JPO; DERWENT	OR	OFF	2002/02/05 08:51

S34	3066	optically adj align$5	USPAT; EPO; JPO; DERWENT	OR	OFF	2002/02/05 08:56
S35	612	(optically adj align$5) and semiconductor	USPAT; EPO; JPO; DERWENT	OR	OFF	2002/02/05 08:57
S36	8	(("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697") or ("5858815") or ("5137836") or ("4781969")).PN.	USPAT; USOCR	OR	OFF	2003/06/02 08:10
S37	10260	wood.inv.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/07/03 08:13
S38	539	wood.inv. and alan	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/07/03 08:13
S39	232	(wood.inv. and alan) and (micron adj technology)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/07/03 08:14
S40	1	("6268650").PN.	USPAT; USOCR	OR	OFF	2004/04/06 13:58
S41	425	(438/15).CCLS.	USPAT; USOCR	OR	OFF	2002/07/08 08:43
S42	331	(438/113).CCLS.	USPAT; USOCR	OR	OFF	2002/07/08 08:57
S43	140	(438/110).CCLS.	USPAT; USOCR	OR	OFF	2002/07/08 08:57
S44	90	(438/114).CCLS.	USPAT; USOCR	OR	OFF	2002/07/08 08:57
S45	425	(438/15).CCLS.	USPAT; USOCR	OR	OFF	2002/07/08 08:43
S46	331	(438/113).CCLS.	USPAT; USOCR	OR	OFF	2002/07/08 08:57
S47	140	(438/110).CCLS.	USPAT; USOCR	OR	OFF	2002/07/08 08:57
S48	90	(438/114).CCLS.	USPAT; USOCR	OR	OFF	2002/07/08 14:32

S49	13	(("6389689") or ("5977629") or ("5796170") or ("6326700") or ("6268650") or ("5858815") or ("5817535") or ("5770032") or ("4781969") or ("5073840") or ("5696033") or ("5834839") or ("6160714")).PN.	USPAT; USOCR	OR	OFF	2002/07/08 10:35
S50	8	(("6309909") or ("5858815") or ("5137836") or ("6077757") or ("6326697") or ("6165885") or ("5834320") or ("4781969")).PN.	USPAT; USOCR	OR	OFF	2002/07/09 09:56
S53	19	wafer adj (bond$3 or attach$3) near4 (dielectric adj (layer or film))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/19 14:07
S55	963	438/15,110,113,114.ccls.	USPAT	OR	OFF	2002/12/19 14:38
S56	1212	438/15,110,113,114.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/19 14:38
S58	9	(wafer adj (dielectric adj (layer or film))) same test$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/20 08:18
S59	13	(("5834839") or ("6389689") or ("6160714") or ("5977629") or ("6326700") or ("6268650") or ("5858815") or ("5817535") or ("5770032") or ("5796170") or ("4781969") or ("5073840") or ("5696033")).PN.	USPAT; USOCR	OR	OFF	2002/12/19 15:19
S60	85	wafer same dielectric same test$3 same (cut$3 or dic$3 or slic$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/20 08:42
S61	78	(wafer same dielectric same test$3 same (cut$3 or dic$3 or slic$3)) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/20 09:38
S62	348	(wafer same (dielectric adj (layer or film))) same test$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/20 09:35

S63	322	((wafer same (dielectric adj (layer or film))) same test$3) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/20 09:38
S64	98	(((wafer same (dielectric adj (layer or film))) same test$3) and semiconductor) and (cut$3 or dic$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/12/20 09:39
S65	1	("6424023").PN.	USPAT; USOCR	OR	OFF	2002/12/20 10:24
S66	3	(("5897337") or ("5858815") or ("6389689")).PN.	USPAT; USOCR	OR	OFF	2002/12/23 11:53
S67	2	(("5897337") or ("6389689")).PN.	USPAT; USOCR	OR	OFF	2002/12/23 11:53
S68	9187	((balls adj grid adj arrays) or (BGA)) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/20 07:59
S69	4418	(((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic$4 or cut$4 or separat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/20 08:02
S70	4476	(((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic$4 or cut$4 or separat$5 or saw$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/20 08:04
S71	955	((((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic$4 or cut$4 or separat$5)) and (metal adj (film or layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/20 08:04
S72	970	((((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic$4 or cut$4 or separat$5 or saw$4)) and (metal adj (film or layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/20 08:04
S73	1	("20010052642").PN.	US-PGPUB; USOCR	OR	OFF	2003/05/20 08:12
S74	472	wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/20 08:52

S75	233	(wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/01/12 08:09
S76	212	((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and (dic$5 or cut$6 or saw$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/21 08:23
S77	206	((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and (dic$5 or cut$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/20 09:06
S78	1	(((wafer adj semiconductor) same (metal adj (film or layer)) same (attach$5 or bond$4) same ((balls adj grid adj arrays) or (BGA)) same (dic$4 or cut$4 or separat$5) same (dic$5 or cut$6 or saw$5)) and @ad<="20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/20 10:06
S79	212	((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and (dic$5 or cut$6 or saw$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/21 09:00
S80	172	(((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and (dic$5 or cut$6 or saw$5)) and dic$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/21 09:24
S81	92	(((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and (dic$5 or cut$6 or saw$5)) and (dicing or diced)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/21 09:35

S82	70	((((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and (dic$5 or cut$6 or saw$5)) and (dicing or diced)) and (individual$3 or each)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/21 09:36
S83	70	((((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and (dic$5 or cut$6 or saw$5)) and (dicing or diced)) and (individual$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/21 09:36
S84	6	((((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and (dic$5 or cut$6 or saw$5)) and (dicing or diced)) and (individual$3 adj device)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/05/21 09:37
S85	2	(("6344401") or ("6566745")).PN.	USPAT; USOCR	OR	OFF	2004/01/12 07:56
S86	241	(wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or ("BGA")) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/01/12 08:10
S87	1	((wafer same (metal adj (film or layer)) same (attach$5 or bond$4) same ((balls adj grid adj arrays) or ("BGA")) same semiconductor same (dic$4 or cut$4 or separat$5))) and @ad<="20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/23 10:36
S88	2	(("6153448") or ("20020011859")). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/10/24 12:35
S89	4	(("6153448") or ("20020011859") or ("6064217") or ("5475317")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/10/24 14:07
S90	3	(("6344401") or ("6165885") or ("5834320")).PN.	USPAT; USOCR	OR	OFF	2004/01/12 09:14

S91	244	(wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/01/12 08:03
S92	244	(wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/06 08:33
S93	166	((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and align$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/01/12 08:05
S94	688	(438/455).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/01/12 08:08
S95	12	438/455,456,457,458,459,460,461, 462,464.ccls. and (wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic$4 or cut$4 or separat$5)) and @ad<="20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 09:26
S96	97	"438"/$.ccls. and (wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic$4 or cut$4 or separat$5)) and @ad<="20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 09:23
S97	348	(wafer and ((metal or conductive) adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/06 08:36
S98	229	((wafer and ((metal or conductive) adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and test$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/06 08:36

S99	85	(((wafer and ((metal or conductive) adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and test$4) and (input same output)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/06 08:37
S100	86	(((wafer and ((metal or conductive) adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and test$4) and (input and output)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/06 08:44
S101	78	((((wafer and ((metal or conductive) adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and test$4) and (input and output)) and (cut$5 or dic$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/06 11:21
S102	24	(((((wafer and ((metal or conductive) adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<="20000616") and test$4) and (input and output)) and (cut$5 or dic$6)) and (conductive adj trace)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/06 11:21
S103	5	(("5858815") or ("4781969") or ("5073840") or ("5770032") or ("5817535")).PN.	USPAT; USOCR	OR	OFF	2004/04/08 13:56
S104	10	(("5073840") or ("5817535") or ("5858815") or ("6426642") or ("6214716") or ("6188232") or ("6163956") or ("6150193") or ("6060891") or ("6004867")).PN.	USPAT; USOCR	OR	OFF	2004/04/08 13:29
S105	10	(("5073840" "5817535" "5858815" "6426642" "6214716" "6188232" "6163956" "6150193" "6060891" "6004867").pn.) and test$5 and (cut$5 or dic$6 or seperat$5 or saw$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/08 09:30

S10 6	6	(((("5073840" "5817535" "5858815" "6426642" "6214716" "6188232" "6163956" "6150193" "6060891" "6004867").pn.) and test$5 and (cut$5 or dic$6 or seperat$5 or saw$4)) and cut$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/08 09:30
S10 7	1134	"438"/$.ccls. and test$6 and (dic$4) and @ad<"20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 09:25
S10 8	2169	"257"/$.ccls. and test$6 and (dic$4) and @ad<"20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 09:25
S10 9	203	438/15,110,113,114.ccls. and test$6 and (dic$4) and @ad<"20000616"	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/06 09:25
S11 0	199	438/455,456,457,458,459,460,461, 462,464.ccls. and test$6 and (dic$4) and @ad<"20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/08 09:53
S11 1	2	("6261919").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/06 13:56
S11 2	2	("6429530").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/07 08:13
S11 3	7	(("6163956") or ("6153448") or ("6064217") or ("6344401") or ("4781969") or ("5137836") or ("20010052642")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/10/07 10:04
S11 4	1	("5989982").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/10/07 13:52
S11 5	1	("5897334").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/10/07 13:52
S12 1	1	("6242808").PN.	USPAT; USOCR	OR	OFF	2002/07/09 09:57
S12 4	1	("6461891").PN.	USPAT; USOCR	OR	OFF	2003/05/21 09:19

S12 5	1	("6232663").PN.	USPAT; USOCR	OR	OFF	2003/06/02 09:05
S12 6	1	("6417047").PN.	USPAT; USOCR	OR	OFF	2003/06/02 09:37
S12 7	1	("6613669").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/10/24 14:07
S12 9	21720	"438"/$.ccls. and align$5 and @ad<="20000616"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/01/12 08:10
S14 2	913	257/276,625,675,706,717,718,720, 722,796.ccls. and (heat adj sink) and fins and @ad<="20020311"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/08 09:15
S14 3	66	257/276,625,675,706,717,718,720, 722,796.ccls. and (heat adj sink) and fins and @ad<="20020311" and (planar adj surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/08 09:15
S14 4	76	438/122,123.ccls. and (heat adj sink) and fins and @ad<="20020311"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/08 09:16
S14 5	96	("5073840" "5817535" "5858815" "6426642" "6214716" "6188232" "6163956" "6150193" "6060891" "6004867".pn.) and test$5 and (cut$5 or dic$6 or seperat$5 or saw$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/08 09:29
S14 7	2	(("6113724") or ("20020181224")). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/04/08 10:17
S14 8	1	("4752858").PN.	USPAT; USOCR	OR	OFF	2004/04/08 13:30
S14 9	1	("6314639").PN.	USPAT; USOCR	OR	OFF	2004/04/08 13:56
S15 0	16	(("5242855") or ("3918148") or ("6175084") or ("5134539") or ("6297553") or ("5143865") or ("6389689") or ("6479887")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/06 12:01

S15 2	12	(("6163956") or ("6153448") or ("6064217") or ("6334401") or ("4781969") or ("5137836")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/07 08:15
S15 5	8	(("5242855") or ("3918148") or ("6175084") or ("5134539") or ("6297553") or ("5143865") or ("6389689") or ("6479887")).PN.	USPAT; USOCR	OR	OFF	2004/10/07 10:06
S16 1	105	438/106,107,110,113,114.ccls. and metal and (through-hole)	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/07 12:30
S16 2	730	"438"/$.ccls. and metal and (through-hole)	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/07 12:31
S16 3	429	"257"/$.ccls. and (metal near10 (through-hole))	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/07 12:32
S16 4	978	semiconductor and (metal near10 (through-hole))	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/07 12:32
S16 5	214	"438"/$.ccls. and (metal near10 (through-hole))	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/07 12:13
S16 6	103	438/106,107,110,113,114.ccls. and metal and (through-hole) and (chip or die or dice or ((integrated adj circuit) or ("IC")))	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/07 12:31
S16 7	512	"438"/$.ccls. and metal and (through-hole) and (chip or die or dice or ((integrated adj circuit) or ("IC")))	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/07 12:32
S16 8	332	"257"/$.ccls. and (metal near10 (through-hole)) and (chip or die or dice or ((integrated adj circuit) or ("IC")))	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/07 12:32
S16 9	535	semiconductor and (metal near10 (through-hole)) and (chip or die or dice or ((integrated adj circuit) or ("IC")))	USPAT; EPO; JPO; DERWENT	OR	OFF	2004/10/07 12:32
S17 0	9	(("5242855") or ("3918148") or ("6175084") or ("5134539") or ("6297553") or ("5143865") or ("6389689") or ("6479887") or ("20010052642")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/10/07 14:03

S17 1	2	("5242855").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/06 13:47
S17 2	2	("6268236").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/08 09:19
S17 3	10	(("5242855") or ("3918148") or ("6175084") or ("5134539") or ("6297553") or ("5143865") or ("6389689") or ("6479887") or ("6252298") or ("20010052642")). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/10/08 09:29